

MOSFET - N-Channel, POWERTRENCH®

75 V, 235 A, 3.2 m Ω

FDA032N08

Description

This N-Channel MOSFET is produced using **onsemi**'s advanced POWERTRENCH process that has been tailored to minimize the on-state resistance while maintaining superior switching performance.

Features

- $R_{DS(on)} = 2.5 \text{ m}\Omega \text{ (Typ.)} @ V_{GS} = 10 \text{ V, } I_D = 75 \text{ A}$
- Fast Switching Speed
- Low Gate Charge
- High Performance Trench Technology for Extremely Low R_{DS(on)}
- High Power and Current Handling Capability
- RoHS Compliant

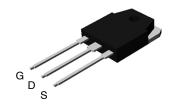
Applications

- Synchronous Rectification for ATX / Server / Telecom PSU
- Battery Protection Circuit
- Motor Drives and Uninterruptible Power Supplies

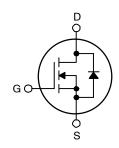
MOSFET MAXIMUM RATINGS ($T_C = 25^{\circ}C$ unless otherwise noted)

Symbol	Parameter	Value	Unit	
V _{DSS}	Drain to Source Voltage	75	V	
V _{GSS}	Gate to Source Voltage	±20	V	
I _D	Drain Current Continuous (T_C = 25°C, Silicon Limited) Continuous (T_C = 100°C, Silicon Limited) Continuous (T_C = 25°C, Package Limited)	235 165 120	Α	
I _{DM}	Drain Current - Pulsed (Note 1)	940	Α	
E _{AS}	Single Pulsed Avalanche Energy (Note 2)	1995	mJ	
dv/dt	dt Peak Diode Recovery dv/dt (Note 3)		V/ns	
P _D	Power Dissipation (T _C = 25°C) – Derate above 25°C	375 2.5	W W/°C	
T _J , T _{STG}	Operating and Storage Temperature Range	–55 to +175	°C	
TL	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		°C	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.



TO-3P-3LD / EIAJ SC-65, ISOLATED CASE 340BZ



MARKING DIAGRAM

FDA 032N08 AYWWZZ

FDA032N08 = Specific Device Code A = Assembly Location

YWW = Date Code (Year and Week)

ZZ = Assembly Lot

ORDERING INFORMATION

Device	Package	Shipping
FDA032N08	TO-3P-3L (Pb-Free)	450 Units / Tube

THERMAL CHARACTERISTICS

Symbol	Parameter	FDA032N08	Unit
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max	0.4	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max	40	°C/W

FLECTRICAL CHARACTERISTICS (T.

	CAL CHARACTERISTICS (T _C = 25°C, t	,	T	I _		1
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
OFF CHAR	ACTERISTIC				_	
BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 250 \mu A$, $V_{GS} = 0 V$, $T_C = 25^{\circ}C$	75	-	-	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	I _D = 250 μA, Referenced to 25°C	-	0.05	-	V/°C
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 75 V, V _{GS} = 0 V	-	-	1	μΑ
		V _{DS} = 75 V, T _C = 150°C	-	_	10	
I _{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 20 \text{ V}, V_{DS} = 0 \text{ V}$	-	-	±100	nA
ON CHARA	CTERISTICS		-			
V _{GS(th)}	Gate Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250 \mu A$	2.5	3.5	4.5	V
R _{DS(on)}	Static Drain to Source On-Resistance	V _{GS} = 10 V, I _D = 75 A	-	2.5	3.2	mΩ
9FS	Forward Transconductance	V _{DS} = 20 V, I _D = 75 A	-	180	-	S
DYNAMIC (CHARACTERISTICS		•		•	
C _{iss}	Input Capacitance	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz	_	11400	15160	pF
C _{oss}	Output Capacitance		-	1360	1810	pF
C _{rss}	Reverse Transfer Capacitance		-	595	800	pF
Q _{g(TOT)}	Total Gate Charge at 10 V	V _{DS} = 60 V, I _D = 75 A,	-	169	220	nC
Q_{gs}	Gate to Source Gate Charge	V _{GS} = 10 V (Note 4)	-	60	-	nC
Q_{gd}	Gate to Drain "Miller" Charge		-	47	-	nC
SWITCHING	G CHARACTERISTICS					
t _{d(on)}	Turn-On Delay Time	V _{DD} = 37.5 V, I _D = 75 A,	_	230	470	ns
t _r	Turn-On Rise Time	$R_G = 25 \Omega, V_{GS} = 10 V \text{ (Note 4)}$	_	191	392	ns
t _{d(off)}	Turn-Off Delay Time	1	_	335	680	ns
t _f	Turn-Off Fall Time	7	_	121	252	ns
DRAIN-SO	URCE DIODE CHARACTERISTICS		•			
IS	Maximum Continuous Drain to Source Diode Forward Current		-	_	235	Α
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	940	Α
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 75 A	-	-	1.3	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 75 A,	-	53	-	ns
Q _{rr}	Reverse Recovery Charge	$dI_F/dt = 100 A/\mu s$	-	77	_	nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Repetitive Rating: Pulse width limited by maximum junction temperature.

2. L = 0.71 mH, $I_{AS} = 75$ A, $V_{DD} = 50$ V, $R_{G} = 25$ Ω , Starting $T_{J} = 25^{\circ}C$.

3. $I_{SD} \le 75$ A, $I_{SD} \le 75$ A, $I_{SD} \le 8V_{DSS}$, Starting $I_{SD} \le 75$ A. Essentially independent of operating temperature typical characteristics.

TYPICAL PERFORMANCE CHARACTERISTICS

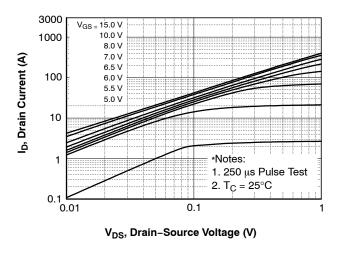
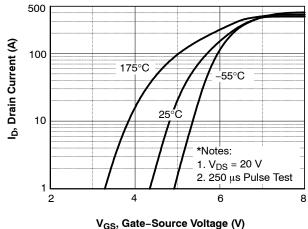


Figure 1. On-Region Characteristics



V_{GS}, Gate-Source voltage (V)

Figure 2. Transfer Characteristics

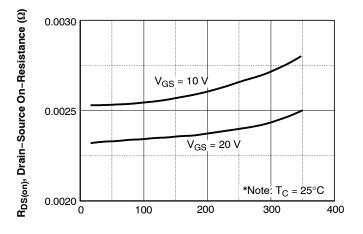
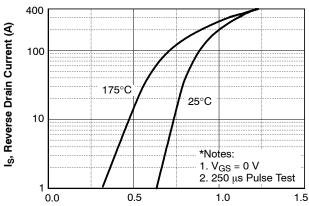


Figure 3. On–Resistance Variation vs. Drain Current and Gate Voltage

I_D, Drain Current (A)



V_{SD}, Source-Drain Voltage (V)

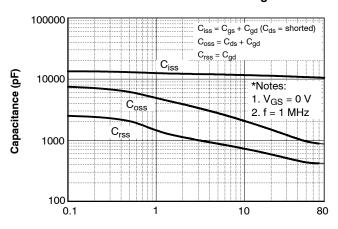
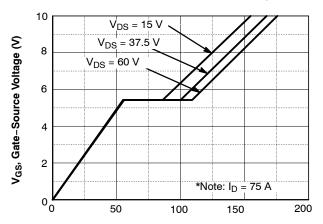


Figure 5. Capacitance Characteristics

V_{DS}, Drain-Source Voltage (V)

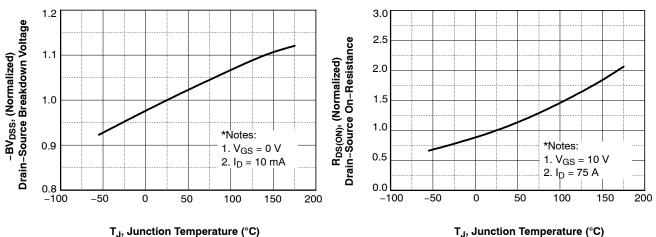




Q_G, Total Gate Charge (nC)

Figure 6. Gate Charge Characteristics

TYPICAL PERFORMANCE CHARACTERISTICS (continued)



T_J, Junction Temperature (°C)

Figure 7. Breakdown Voltage Variation vs. Temperature



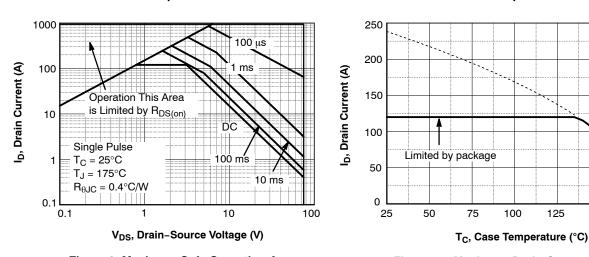


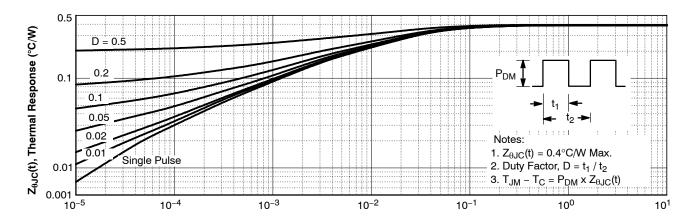
Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case **Temperature**

125

150

175



t₁, Rectangular Pulse Duration (s)

Figure 11. Transient Thermal Response Curve

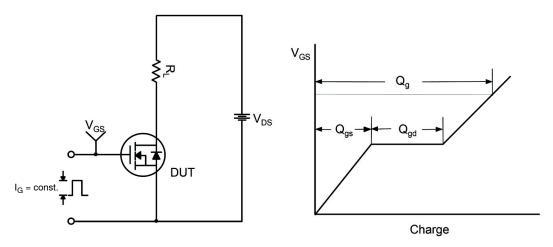


Figure 12. Gate Charge Test Circuit & Waveform

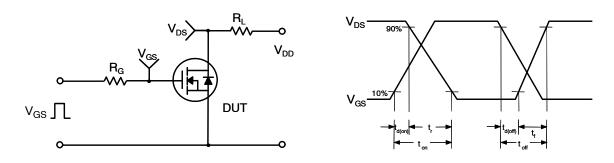


Figure 13. Resistive Switching Test Circuit & Waveforms

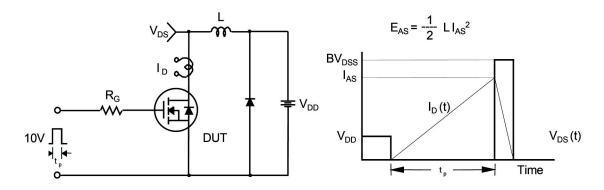
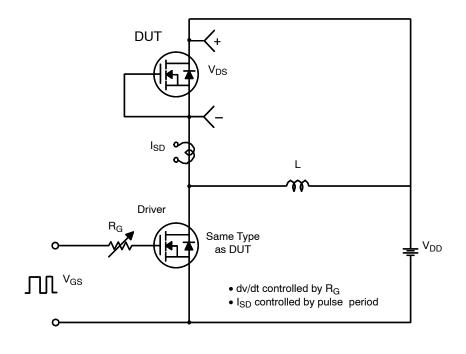


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



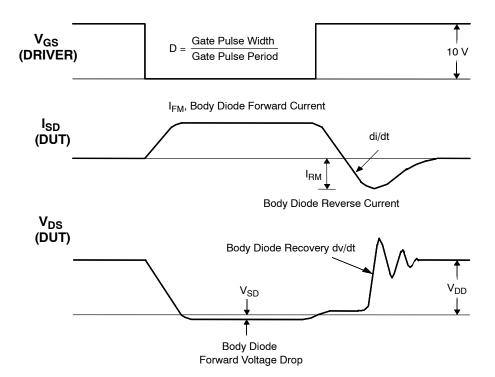


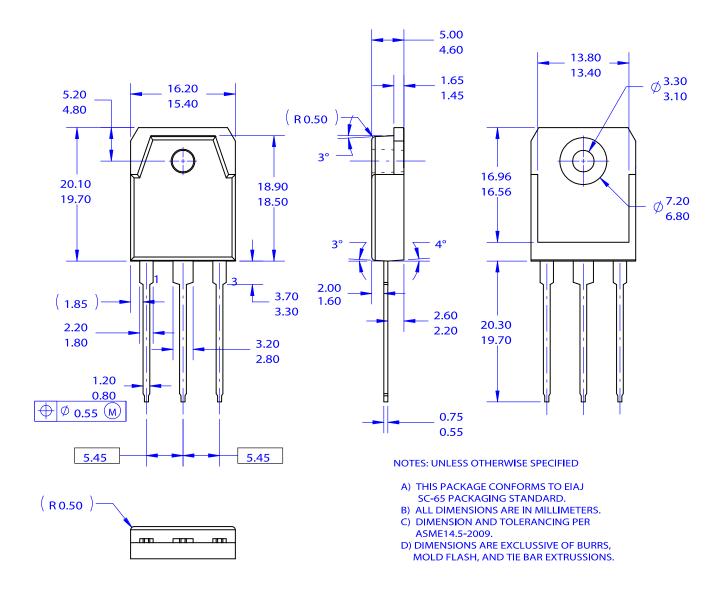
Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

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